

Silicon Diffused Power Transistor**BUJ105AX****GENERAL DESCRIPTION**

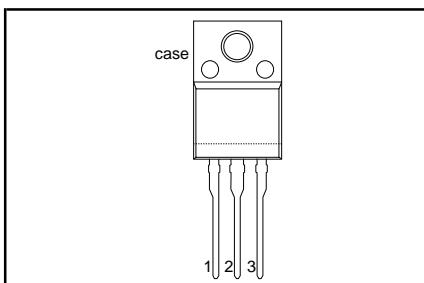
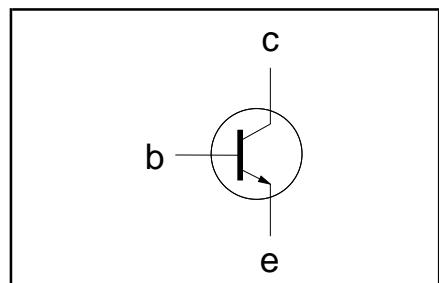
High-voltage, high-speed planar-passivated npn power switching transistor in a plastic full-pack envelope intended for use in high frequency electronic lighting ballast applications, converters, inverters, switching regulators, motor control systems, etc.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	700	V
V_{CBO}	Collector-Base voltage (open emitter)		-	700	V
V_{CEO}	Collector-emitter voltage (open base)		-	400	V
I_C	Collector current (DC)		-	8	A
I_{CM}	Collector current peak value		-	16	A
P_{tot}	Total power dissipation		-	32	W
V_{CEsat}	Collector-emitter saturation voltage		0.3	1.0	V
h_{FEsat}			11	15	
t_f	Fall time		20	50	ns

PINNING - SOT186A

PIN	DESCRIPTION
1	base
2	collector
3	emitter
case	isolated

PIN CONFIGURATION**SYMBOL****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CESM}	Collector to emitter voltage	$V_{BE} = 0 \text{ V}$	-	700	V
V_{CEO}	Collector to emitter voltage (open base)		-	400	V
V_{CBO}	Collector to base voltage (open emitter)		-	700	V
I_C	Collector current (DC)		-	8	A
I_{CM}	Collector current peak value		-	16	A
I_B	Base current (DC)		-	4	A
I_{BM}	Base current peak value		-	8	A
P_{tot}	Total power dissipation		-	32	W
T_{stg}	Storage temperature		-65	150	°C
T_j	Junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R_{thj-hs}	Junction to mounting base	With heatsink compound	-	3.95	K/W
R_{thj-a}	Junction to ambient	in free air	55	-	K/W

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ISOLATION LIMITING VALUE & CHARACTERISTIC $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	$f = 50-60 \text{ Hz}$; sinusoidal waveform; $R.H. \leq 65\%$; clean and dustfree	-		2500	V
C_{isol}	Capacitance from T2 to external heatsink	$f = 1 \text{ MHz}$	-	10	-	pF

STATIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CES}, I_{CBO} I_{CES}	Collector cut-off current ¹	$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$ $V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$ $T_j = 125^\circ\text{C}$	-	-	0.2 0.5	mA mA
I_{CEO} I_{EBO} $V_{CEO}sust$	Collector cut-off current Emitter cut-off current Collector-emitter sustaining voltage	$V_{CEO} = V_{CEO Mmax} (400V)$ $V_{EB} = 9 \text{ V}; I_c = 0 \text{ A}$ $I_B = 0 \text{ A}; I_c = 10 \text{ mA};$ $L = 25 \text{ mH}$	- - 400	- -	0.1 1	mA mA V
V_{CEsat} V_{BEsat} h_{FE} h_{FE} h_{FEsat}	Collector-emitter saturation voltage Base-emitter saturation voltage DC current gain	$I_c = 4.0 \text{ A}; I_B = 0.8 \text{ A}$ $I_c = 4.0 \text{ A}; I_B = 0.8 \text{ A}$ $I_c = 1 \text{ mA}; V_{CE} = 5 \text{ V}$ $I_c = 500 \text{ mA}; V_{CE} = 5 \text{ V}$ $I_c = 4.0 \text{ A}; V_{CE} = 5 \text{ V}$	- - 10 13 8	0.3 1.0 14 23 11	1.0 1.5 34 36 15	V V V V

DYNAMIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
t_{on} t_s t_f	Switching times (resistive load) Turn-on time Turn-off storage time Turn-off fall time	$I_{Con} = 5 \text{ A}; I_{Bon} = -I_{Boff} = 1 \text{ A};$ $R_L = 75 \text{ ohms}; V_{BB2} = 4 \text{ V};$	0.65 1.8 0.3	1 2.5 0.5	μs μs μs
t_s t_f	Switching times (inductive load) Turn-off storage time Turn-off fall time	$I_{Con} = 5 \text{ A}; I_{Bon} = 1 \text{ A}; L_B = 1 \mu\text{H};$ $-V_{BB} = 5 \text{ V}$	1.2 20	1.7 50	μs ns
t_s t_f	Switching times (inductive load) Turn-off storage time Turn-off fall time	$I_{Con} = 5 \text{ A}; I_{Bon} = 1 \text{ A}; L_B = 1 \mu\text{H};$ $-V_{BB} = 5 \text{ V}; T_j = 100^\circ\text{C}$	1.4 25	1.9 100	μs ns

¹ Measured with half sine-wave voltage (curve tracer).

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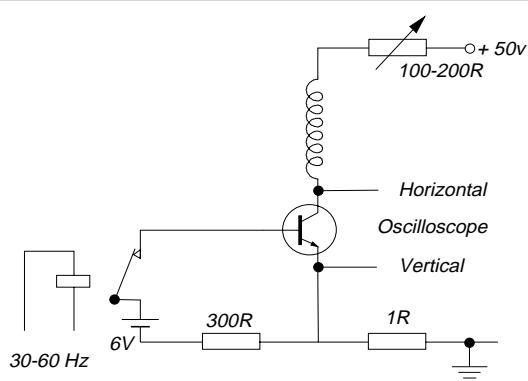
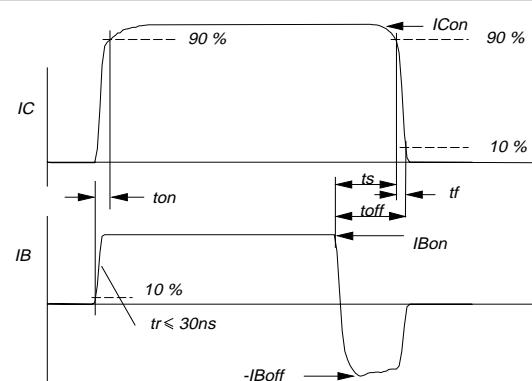
Fig.1. Test circuit for V_{CEO}^{sust} .

Fig.4. Switching times waveforms with resistive load.

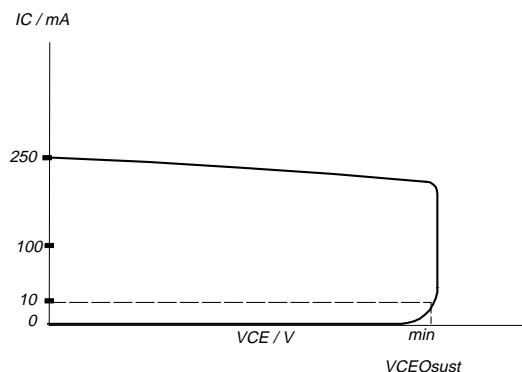
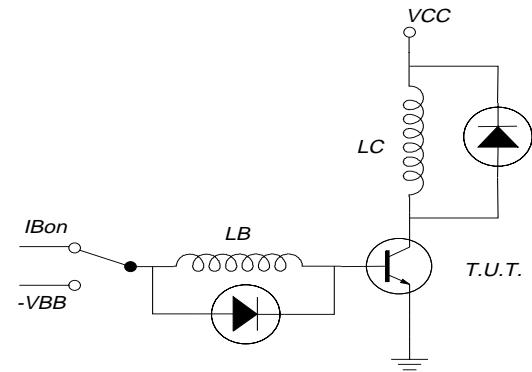
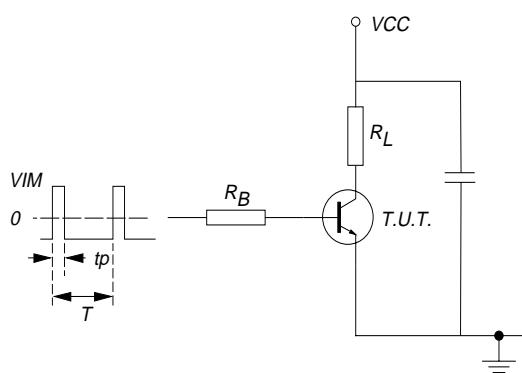
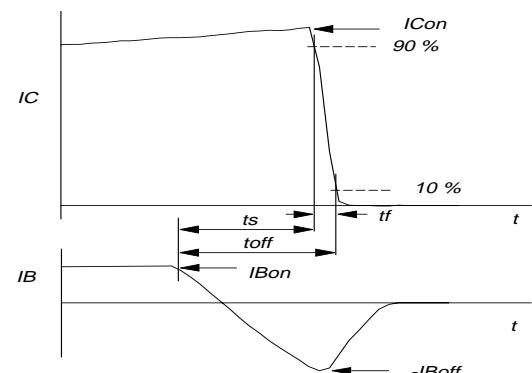
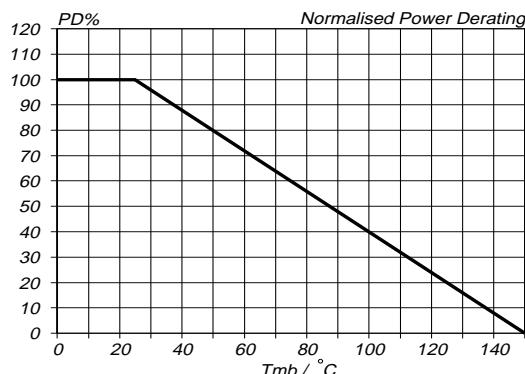
Fig.2. Oscilloscope display for V_{CEO}^{sust} .Fig.5. Test circuit inductive load.
 $V_{CC} = 300\text{ V}$; $-V_{BE} = 5\text{ V}$; $L_C = 200\text{ }\mu\text{H}$; $L_B = 1\text{ }\mu\text{H}$ Fig.3. Test circuit resistive load. $V_{IM} = -6$ to $+8\text{ V}$
 $V_{CC} = 250\text{ V}$; $t_p = 20\text{ }\mu\text{s}$; $\delta = t_p/T = 0.01$.
 R_B and R_L calculated from I_{Con} and I_{Bon} requirements.

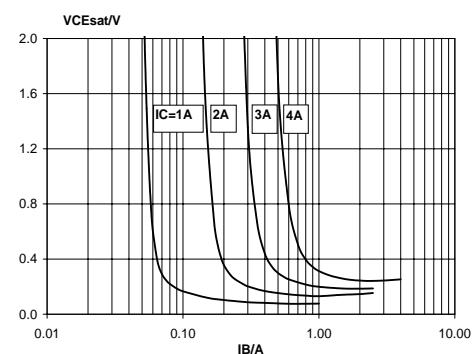
Fig.6. Switching times waveforms with inductive load.

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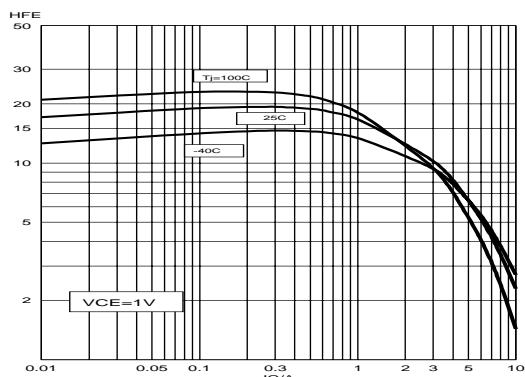
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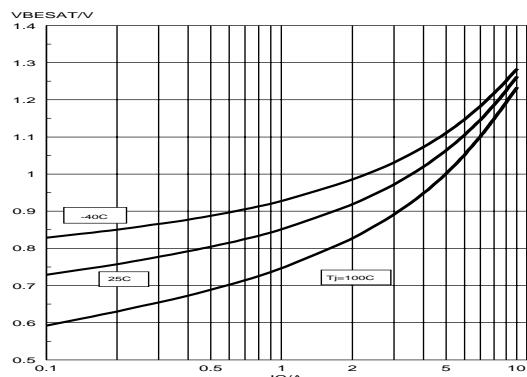
*Fig.7. Normalised power dissipation.
PD% = 100-PD/PD_{25°C} = f(T_{hs})*



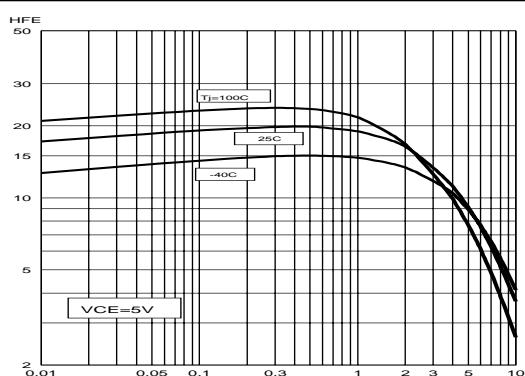
*Fig.10. Collector-Emitter saturation voltage.
Solid lines = typ values, $V_{CEsat} = f(IB)$; $T_j=25^\circ C$.*



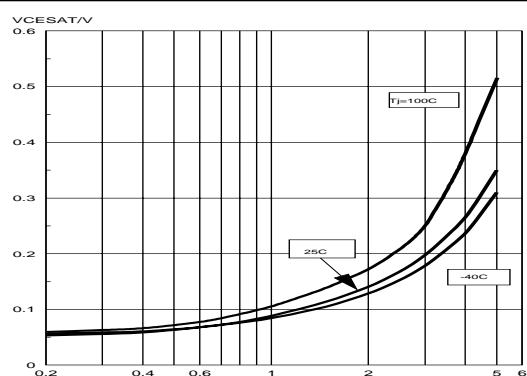
*Fig.8. Typical DC current gain. $h_{FE} = f(I_C)$
parameter V_{CE}*



*Fig.11. Base-Emitter saturation voltage.
Solid lines = typ values, $V_{BESAT} = f(IC)$; at $IC/IB = 4$.*



*Fig.9. Typical DC current gain. $h_{FE} = f(I_C)$
parameter V_{CE}*



*Fig.12. Collector-Emitter saturation voltage.
Solid lines = typ values, $V_{CESAT} = f(IC)$; at $IC/IB = 4$.*

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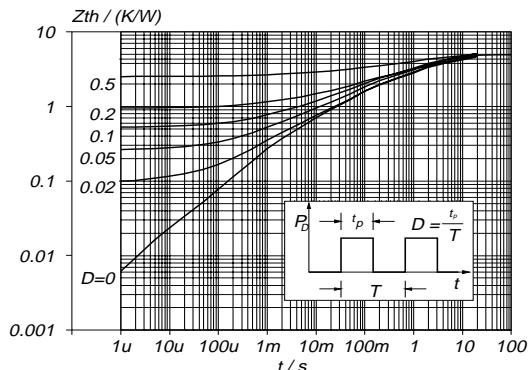


Fig.13. Transient thermal impedance.
 $Z_{th(j-hs)} = f(t)$; parameter $D = t_p/T$

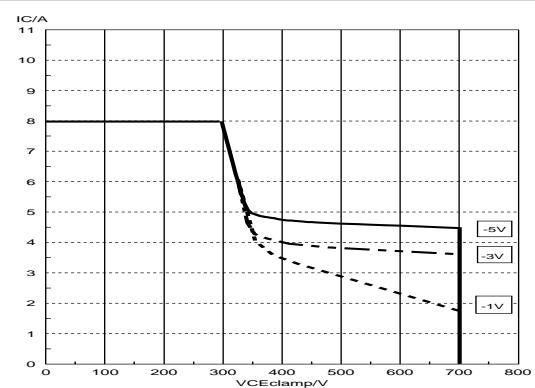


Fig.15. Reverse bias safe operating area ($T_j < T_{jmax}$)
for $-V_{be} = 5V, 3V \& 1V$.

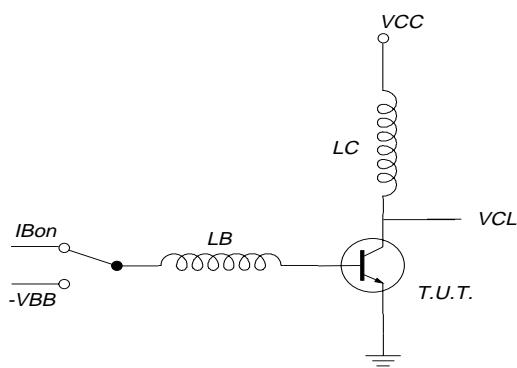


Fig.14. Test circuit for reverse bias safe operating area.

$V_{clamp} < 700V$; $V_{cc} = 150V$; $-V_{be} = 5V, 3V \& 1V$;
 $L_B = 1\mu H$; $L_C = 200\mu H$.

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MECHANICAL DATA*Dimensions in mm*

Net Mass: 2 g

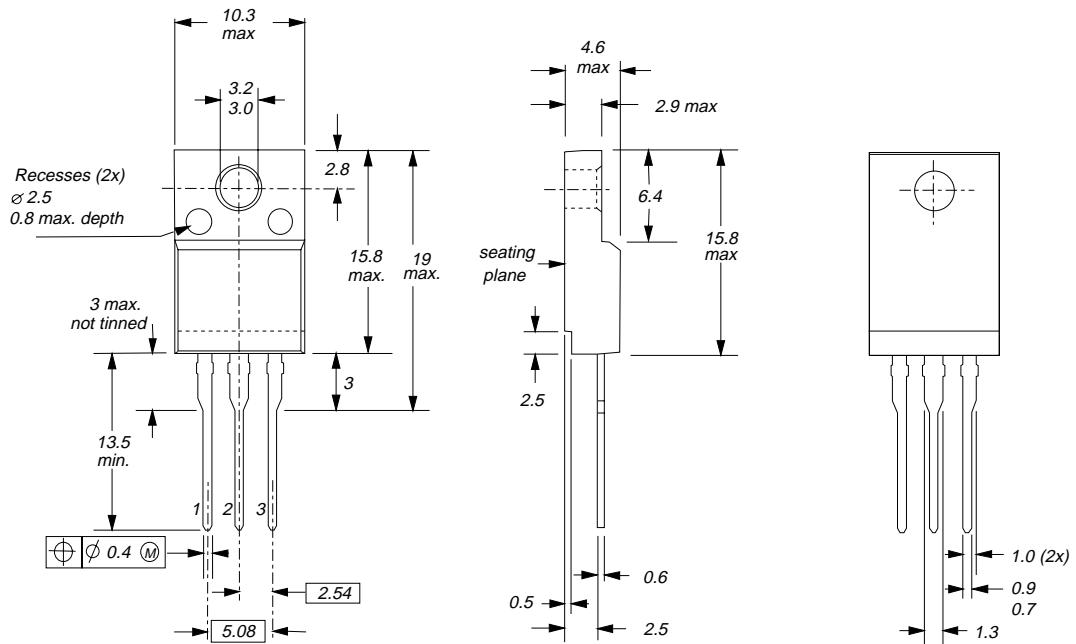


Fig. 16. SOT186A; The seating plane is electrically isolated from all terminals.

Notes

1. Refer to mounting instructions for F-pack envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Silicon Diffused Power Transistor**BUJ105AX****DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	
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